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# 74HC253; 74HCT253

Dual 4-input multiplexer; 3-state

Rev. 5 — 21 January 2015

Product data sheet

## 1. General description

The 74HC253; 74HCT253 are high-speed Si-gate CMOS devices and are pin compatible with Low-power Schottky TTL (LSTTL).

The 74HC253; 74HCT253 provides a dual 4-input multiplexer with 3-state outputs which selects 2 bits of data from up to four sources selected by common data select inputs (S0, S1). The two 4-input multiplexer circuits have individual active LOW output enable inputs ( $\overline{1OE}$ ,  $\overline{2OE}$ ).

The 74HC253 and 74HCT253 are the logic implementation of a 2-pole, 4-position switch, where the position of the switch is determined by the logic levels applied to S0 and S1. The outputs are forced to a high-impedance OFF-state when  $\overline{nOE}$  is HIGH.

The logic equations for the outputs are:

$$1Y = \overline{1OE} \cdot (110 \cdot \overline{S1} \cdot \overline{S0} + 111 \cdot \overline{S1} \cdot S0 + 112 \cdot S1 \cdot \overline{S0} + 113 \cdot S1 \cdot S0)$$

$$2Y = \overline{2OE} \cdot (210 \cdot \overline{S1} \cdot \overline{S0} + 211 \cdot \overline{S1} \cdot S0 + 212 \cdot S1 \cdot \overline{S0} + 213 \cdot S1 \cdot S0)$$

## 2. Features and benefits

- Non-inverting data path
- 3-state outputs interface directly with system bus
- Complies with JEDEC standard no. 7A
- Common select inputs
- Separate output enable inputs
- Input levels:
  - ◆ For 74HC253: CMOS level
  - ◆ For 74HCT253: TTL level
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- Multiple package options
- Specified from -40 °C to +85 °C and from -40 °C to +125 °C



### 3. Applications

- Data selectors
- Data multiplexers

### 4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC253N	-40 °C to +125 °C	DIP16	plastic dual in-line package; 16 leads (300 mil)	SOT38-4
74HCT253N				
74HC253D	-40 °C to +125 °C	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1
74HCT253D				
74HC253DB	-40 °C to +125 °C	SSOP16	plastic shrink small outline package; 16 leads; body width 5.3 mm	SOT338-1
74HCT253DB				

### 5. Functional diagram

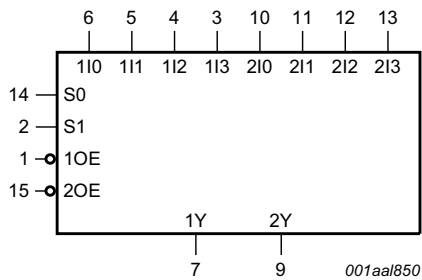


Fig 1. Logic symbol

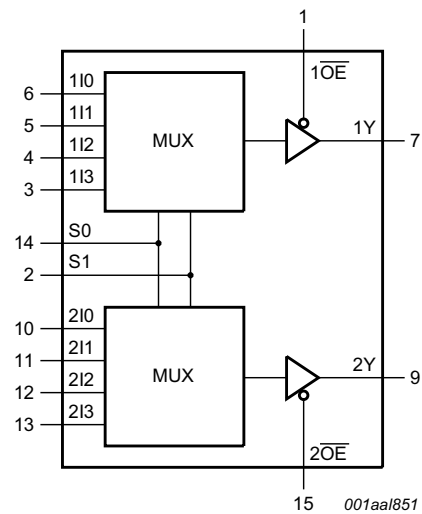


Fig 2. Functional diagram

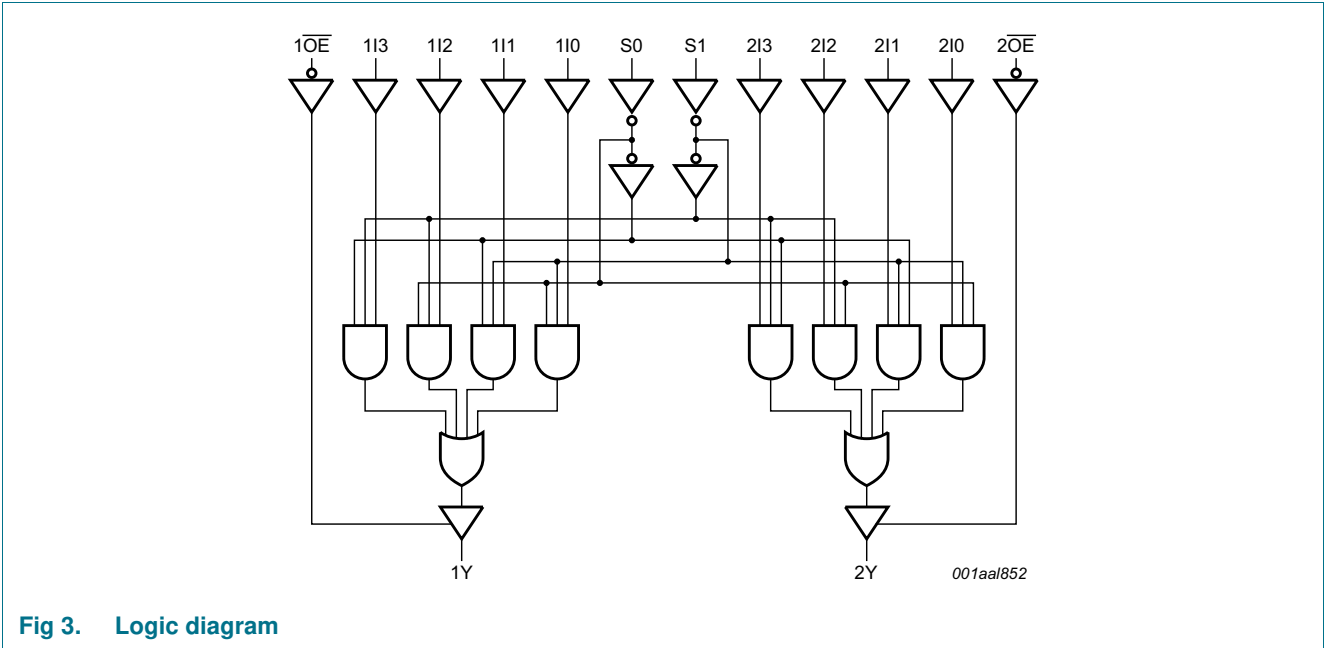


Fig 3. Logic diagram

## 6. Pinning information

### 6.1 Pinning

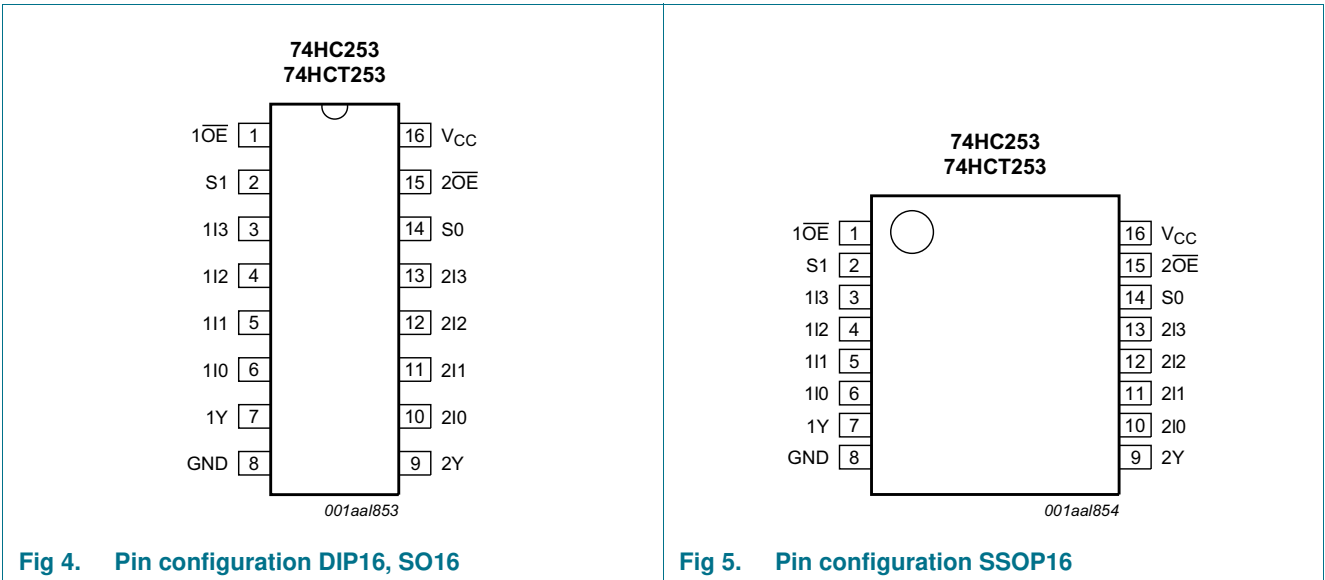


Fig 4. Pin configuration DIP16, SO16

Fig 5. Pin configuration SSOP16

## 6.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
$1\overline{OE}, 2\overline{OE}$	1, 15	output enable inputs (active LOW)
S0, S1	14, 2	data select inputs
1I0, 1I1, 1I2, 1I3	6, 5, 4, 3	data inputs source 1
1Y	7	multiplexer output source 1
GND	8	ground (0 V)
2Y	9	multiplexer output source 2
2I0, 2I1, 2I2, 2I3	10, 11, 12, 13	data inputs source 2
V <sub>CC</sub>	16	supply voltage

## 7. Functional description

Table 3. Function table<sup>[1]</sup>

select inputs		data inputs				output enable	output
S0	S1	nI0	nI1	nI2	nI3	n $\overline{OE}$	nY
X	X	X	X	X	X	H	Z
L	L	L	X	X	X	L	L
L	L	H	X	X	X	L	H
H	L	X	L	X	X	L	L
H	L	X	H	X	X	L	H
L	H	X	X	L	X	L	L
L	H	X	X	H	X	L	H
H	H	X	X	X	L	L	L
H	H	X	X	X	H	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 8. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < -0.5 V or V <sub>I</sub> > V <sub>CC</sub> + 0.5 V	<sup>[1]</sup> -	±20	mA
I <sub>OK</sub>	output clamping current	V <sub>O</sub> < -0.5 V or V <sub>O</sub> > V <sub>CC</sub> + 0.5 V	<sup>[1]</sup> -	±50	mA
I <sub>O</sub>	output current	-0.5 V < V <sub>O</sub> < V <sub>CC</sub> + 0.5 V	-	±35	mA
I <sub>CC</sub>	supply current		-	70	mA
I <sub>GND</sub>	ground current		-70	-	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C



**Table 4. Limiting values ...continued**

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit	
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> = -40 °C to +125 °C				
		DIP16 package	[2]	-	750	mW
		SO16 package	[3]	-	500	mW
		SSOP16 package	[4]	-	500	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] P<sub>tot</sub> derates linearly with 12 mW/K above 70 °C.

[3] P<sub>tot</sub> derates linearly with 8 mW/K above 70 °C.

[4] P<sub>tot</sub> derates linearly with 5.5 mW/K above 60 °C.

## 9. Recommended operating conditions

**Table 5. Recommended operating conditions**

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	74HC253			74HCT253			Unit
			Min	Typ	Max	Min	Typ	Max	
V <sub>CC</sub>	supply voltage		2.0	5.0	6.0	4.5	5.0	5.5	V
V <sub>I</sub>	input voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
V <sub>O</sub>	output voltage		0	-	V <sub>CC</sub>	0	-	V <sub>CC</sub>	V
T <sub>amb</sub>	ambient temperature		-40	-	+125	-40	-	+125	°C
Δt/ΔV	input transition rise and fall rate	V <sub>CC</sub> = 2.0 V	-	-	625	-	-	-	ns/V
		V <sub>CC</sub> = 4.5 V	-	1.67	139	-	1.67	139	ns/V
		V <sub>CC</sub> = 6.0 V	-	-	83	-	-	-	ns/V

## 10. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
<b>74HC253</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 2.0 V	1.5	1.2	-	1.5	-	1.5	-	V
		V <sub>CC</sub> = 4.5 V	3.15	2.4	-	3.15	-	3.15	-	V
		V <sub>CC</sub> = 6.0 V	4.2	3.2	-	4.2	-	4.2	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 2.0 V	-	0.8	0.5	-	0.5	-	0.5	V
		V <sub>CC</sub> = 4.5 V	-	2.1	1.35	-	1.35	-	1.35	V
		V <sub>CC</sub> = 6.0 V	-	2.8	1.8	-	1.8	-	1.8	V

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 2.0 V	1.9	2.0	-	1.9	-	1.9	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 4.5 V	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -20 μA; V <sub>CC</sub> = 6.0 V	5.9	6.0	-	5.9	-	5.9	-	V
		I <sub>O</sub> = -6.0 mA; V <sub>CC</sub> = 4.5 V	3.98	4.32	-	3.84	-	3.7	-	V
		I <sub>O</sub> = -7.8 mA; V <sub>CC</sub> = 6.0 V	5.48	5.81	-	5.34	-	5.2	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>								
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 2.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 4.5 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 20 μA; V <sub>CC</sub> = 6.0 V	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA; V <sub>CC</sub> = 4.5 V	-	0.15	0.26	-	0.33	-	0.4	V
		I <sub>O</sub> = 7.8 mA; V <sub>CC</sub> = 6.0 V	-	0.16	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 6.0 V	-	-	±0.5	-	±5.0	-	±10.0	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 6.0 V	-	-	8.0	-	80	-	160	μA
C <sub>I</sub>	input capacitance		-	3.5	-					pF
<b>74HCT253</b>										
V <sub>IH</sub>	HIGH-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	2.0	1.6	-	2.0	-	2.0	-	V
V <sub>IL</sub>	LOW-level input voltage	V <sub>CC</sub> = 4.5 V to 5.5 V	-	1.2	0.8	-	0.8	-	0.8	V
V <sub>OH</sub>	HIGH-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = -20 μA	4.4	4.5	-	4.4	-	4.4	-	V
		I <sub>O</sub> = -6 mA	3.98	4.32	-	3.84	-	3.7	-	V
V <sub>OL</sub>	LOW-level output voltage	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 4.5 V								
		I <sub>O</sub> = 20 μA	-	0	0.1	-	0.1	-	0.1	V
		I <sub>O</sub> = 6.0 mA	-	0.15	0.26	-	0.33	-	0.4	V
I <sub>I</sub>	input leakage current	V <sub>I</sub> = V <sub>CC</sub> or GND; V <sub>CC</sub> = 5.5 V	-	-	±0.1	-	±1.0	-	±1.0	μA
I <sub>OZ</sub>	OFF-state output current	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>CC</sub> = 5.5 V; V <sub>O</sub> = V <sub>CC</sub> or GND per input pin; other inputs at V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A	-	-	±0.5	-	±5.0	-	±10	μA
I <sub>CC</sub>	supply current	V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0 A; V <sub>CC</sub> = 5.5 V	-	-	8.0	-	80	-	160	μA

**Table 6. Static characteristics ...continued**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			-40 °C to +85 °C		-40 °C to +125 °C		Unit	
			Min	Typ	Max	Min	Max	Min	Max		
$\Delta I_{CC}$	additional supply current	$V_I = V_{CC} - 2.1\text{ V}$ ; other inputs at $V_{CC}$ or GND; $V_{CC} = 4.5\text{ V}$ to $5.5\text{ V}$ ; $I_O = 0\text{ A}$									
			per input pin; 1In, 2In inputs	-	40	144	-	180	-	196	$\mu\text{A}$
			per input pin; $\overline{nOE}$ input	-	110	396	-	495	-	539	$\mu\text{A}$
			per input pin; Sn input	-	110	396	-	495	-	539	$\mu\text{A}$
$C_I$	input capacitance		-	3.5	-					pF	

## 11. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V); For test circuit see [Figure 8](#).

Symbol	Parameter	Conditions	25 °C		-40 °C to +85 °C	-40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
<b>74HC253</b>							
$t_{pd}$	propagation delay	1In to 1Y or 2In to 2Y; see <a href="#">Figure 6</a> <a href="#">[1]</a>					
		$V_{CC} = 2.0\text{ V}$	55	175	220	265	ns
		$V_{CC} = 4.5\text{ V}$	20	35	44	53	ns
		$V_{CC} = 5.0\text{ V}$ ; $C_L = 15\text{ pF}$	17	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	16	30	37	45	ns
		Sn to nY; see <a href="#">Figure 6</a>					
		$V_{CC} = 2.0\text{ V}$	58	175	220	265	ns
		$V_{CC} = 4.5\text{ V}$	21	35	44	53	ns
$t_{en}$	enable time	$\overline{nOE}$ to nY; see <a href="#">Figure 7</a> <a href="#">[2]</a>					
		$V_{CC} = 2.0\text{ V}$	30	100	125	150	ns
		$V_{CC} = 4.5\text{ V}$	11	20	25	30	ns
		$V_{CC} = 6.0\text{ V}$	9	17	21	26	ns
$t_{dis}$	disable time	$\overline{nOE}$ to nY; see <a href="#">Figure 7</a> <a href="#">[3]</a>					
		$V_{CC} = 2.0\text{ V}$	41	150	190	225	ns
		$V_{CC} = 4.5\text{ V}$	15	30	38	45	ns
		$V_{CC} = 6.0\text{ V}$	12	26	33	38	ns
$t_t$	transition time	see <a href="#">Figure 6</a> <a href="#">[4]</a>					
		$V_{CC} = 2.0\text{ V}$	14	60	75	90	ns
		$V_{CC} = 4.5\text{ V}$	5	12	15	18	ns
		$V_{CC} = 6.0\text{ V}$	4	10	13	15	ns



**Table 7. Dynamic characteristics ...continued**

*Voltages are referenced to GND (ground = 0 V); For test circuit see [Figure 8](#).*

Symbol	Parameter	Conditions	25 °C		-40 °C to +85 °C	-40 °C to +125 °C	Unit
			Typ	Max	Max	Max	
C <sub>PD</sub>	power dissipation capacitance	per multiplexer; V <sub>I</sub> = GND to V <sub>CC</sub> [5]	55	-			pF
<b>74HCT253</b>							
t <sub>pd</sub>	propagation delay	1In to 1Y or 2In to 2Y; see <a href="#">Figure 6</a> [1]					
		V <sub>CC</sub> = 4.5 V	20	38	48	57	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	17	-	-		ns
		Sn to nY; see <a href="#">Figure 6</a>					
		V <sub>CC</sub> = 4.5 V	22	40	50	60	ns
		V <sub>CC</sub> = 5.0 V; C <sub>L</sub> = 15 pF	19	-			ns
t <sub>en</sub>	enable time	n $\overline{\text{OE}}$ to nY; V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 7</a> [2]	14	30	38	45	ns
t <sub>dis</sub>	disable time	n $\overline{\text{OE}}$ to nY; V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 7</a> [3]	13	30	38	45	ns
t <sub>t</sub>	transition time	V <sub>CC</sub> = 4.5 V; see <a href="#">Figure 6</a>	5	12	15	18	ns
C <sub>PD</sub>	power dissipation capacitance	per multiplexer; V <sub>I</sub> = GND to V <sub>CC</sub> - 1.5 V [5]	55	-			pF

[1] t<sub>pd</sub> is the same as t<sub>PHL</sub>, t<sub>PLH</sub>.

[2] t<sub>en</sub> is the same as t<sub>PZH</sub>, t<sub>PZL</sub>.

[3] t<sub>dis</sub> is the same as t<sub>PHZ</sub>, t<sub>PLZ</sub>.

[4] t<sub>t</sub> is the same as t<sub>THL</sub>, t<sub>TLH</sub>.

[5] C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW).

$$P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o) \text{ where:}$$

f<sub>i</sub> = input frequency in MHz;

f<sub>o</sub> = output frequency in MHz;

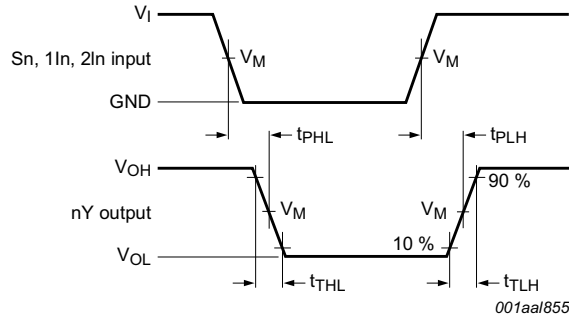
C<sub>L</sub> = output load capacitance in pF;

V<sub>CC</sub> = supply voltage in V;

N = number of inputs switching;

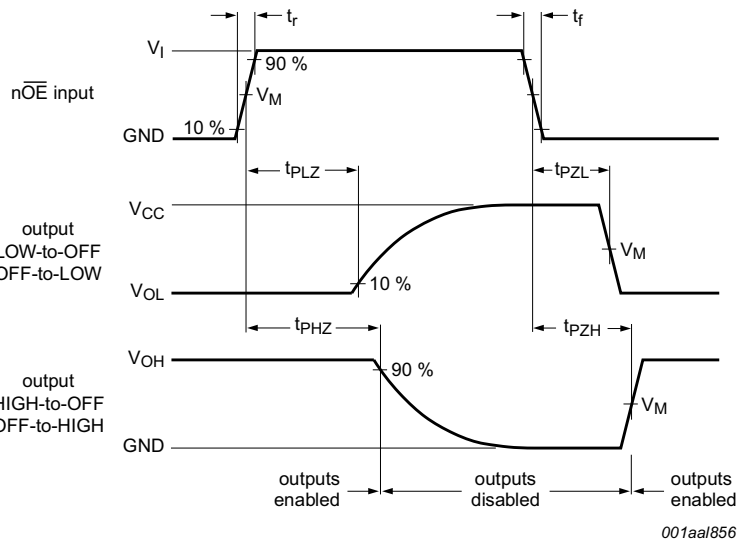
∑(C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of outputs.

12. Waveforms



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Propagation delays input (Sn, 1In, 2In) to output (nY) and output (nY) transition times**



Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. 3-state output enable and disable times**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC253	$0.5V_{CC}$	$0.5V_{CC}$
74HCT253	1.3 V	1.3 V

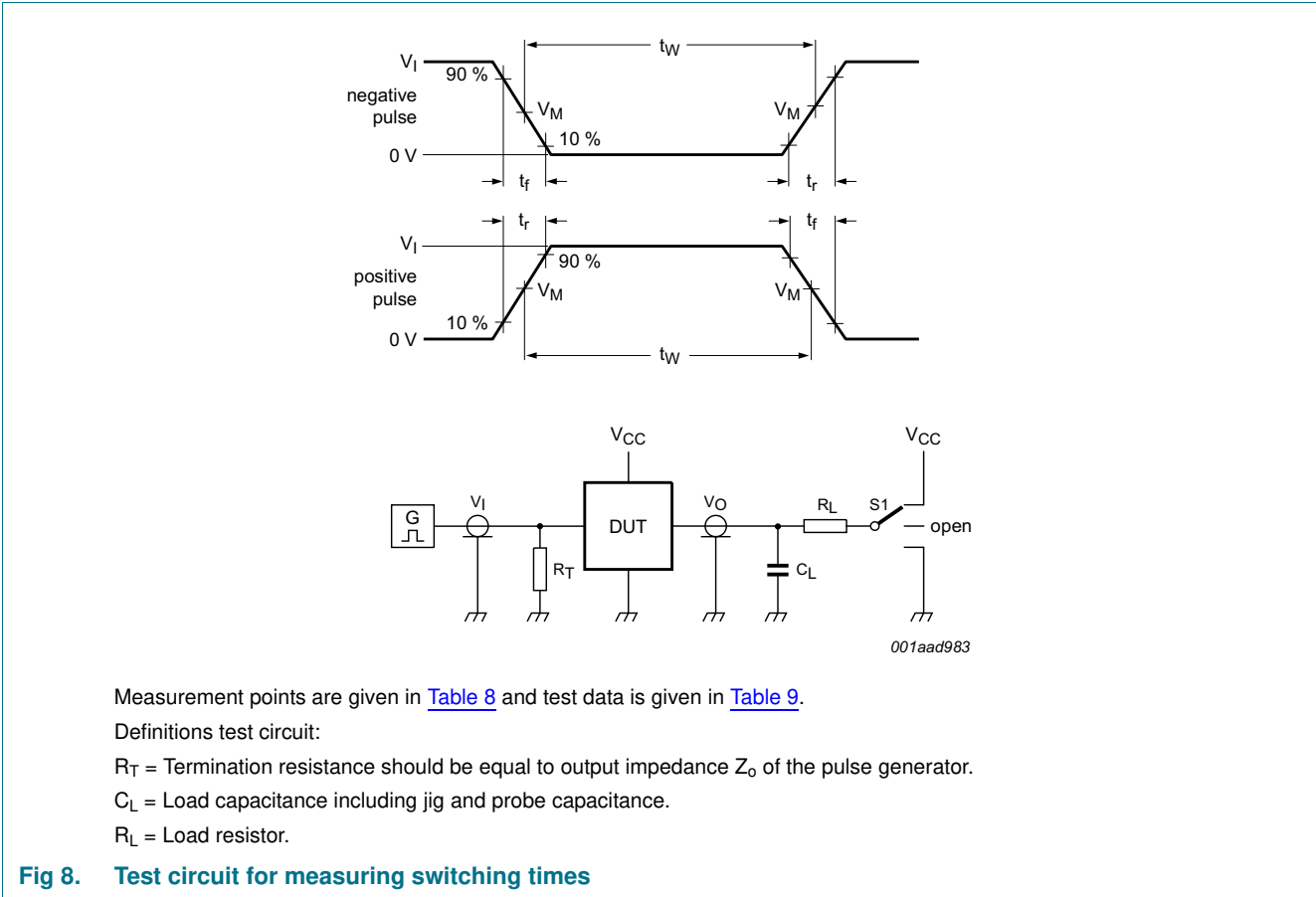


Table 9. Test data

Type	Input		Load		Switch position		
	$V_I$	$t_r, t_f$	$C_L$	$R_L$	$t_{PHL}, t_{PLH}$	$t_{PZH}, t_{PHZ}$	$t_{PZL}, t_{PLZ}$
74HC253	$V_{CC}$	6 ns	50 pF	1 k $\Omega$	open	GND	$V_{CC}$
74HCT253	3 V	6 ns	50 pF	1 k $\Omega$	open	GND	$V_{CC}$

13. Package outline

DIP16: plastic dual in-line package; 16 leads (300 mil)

SOT38-4

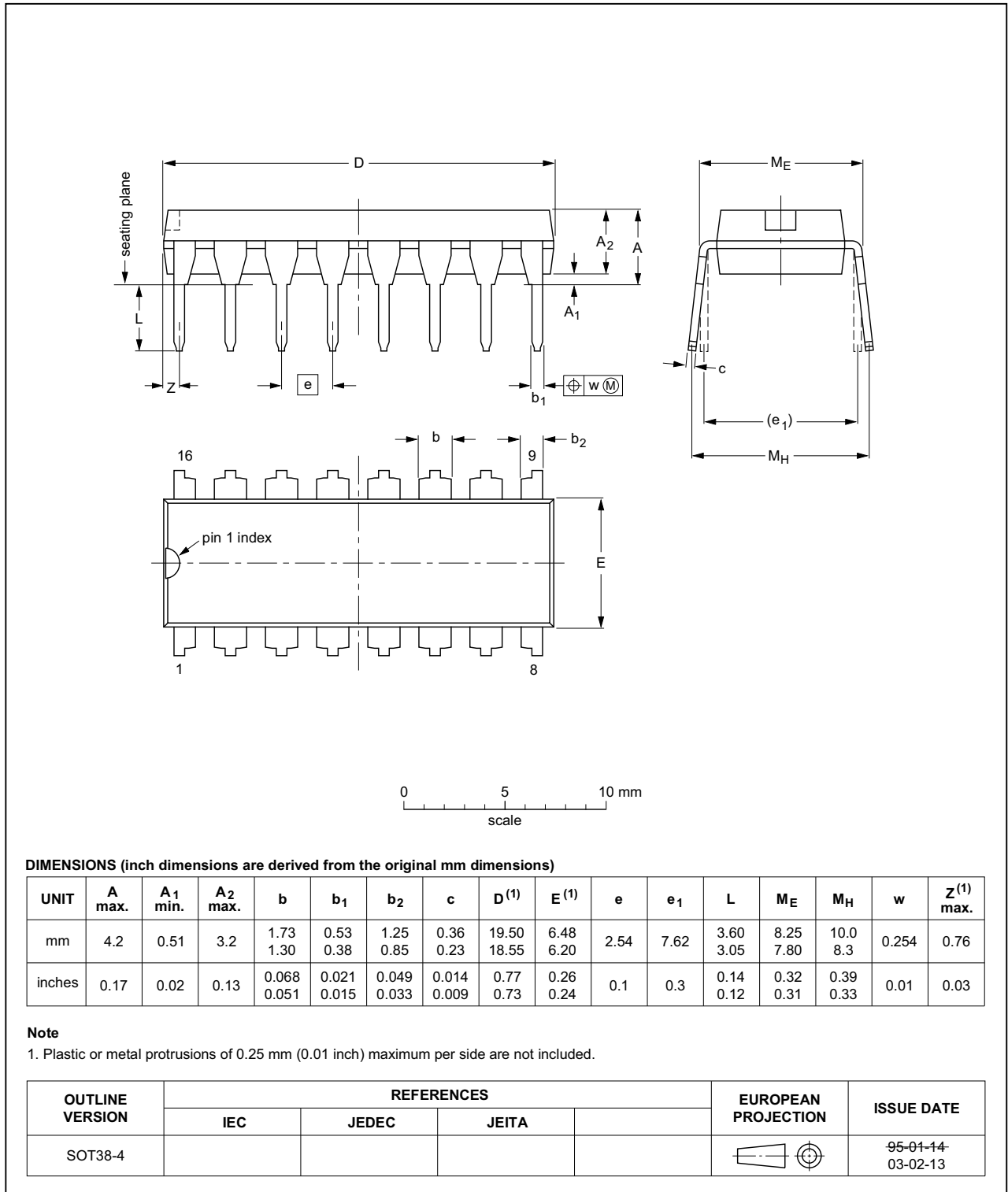


Fig 9. Package outline SOT38-4 (DIP16)

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

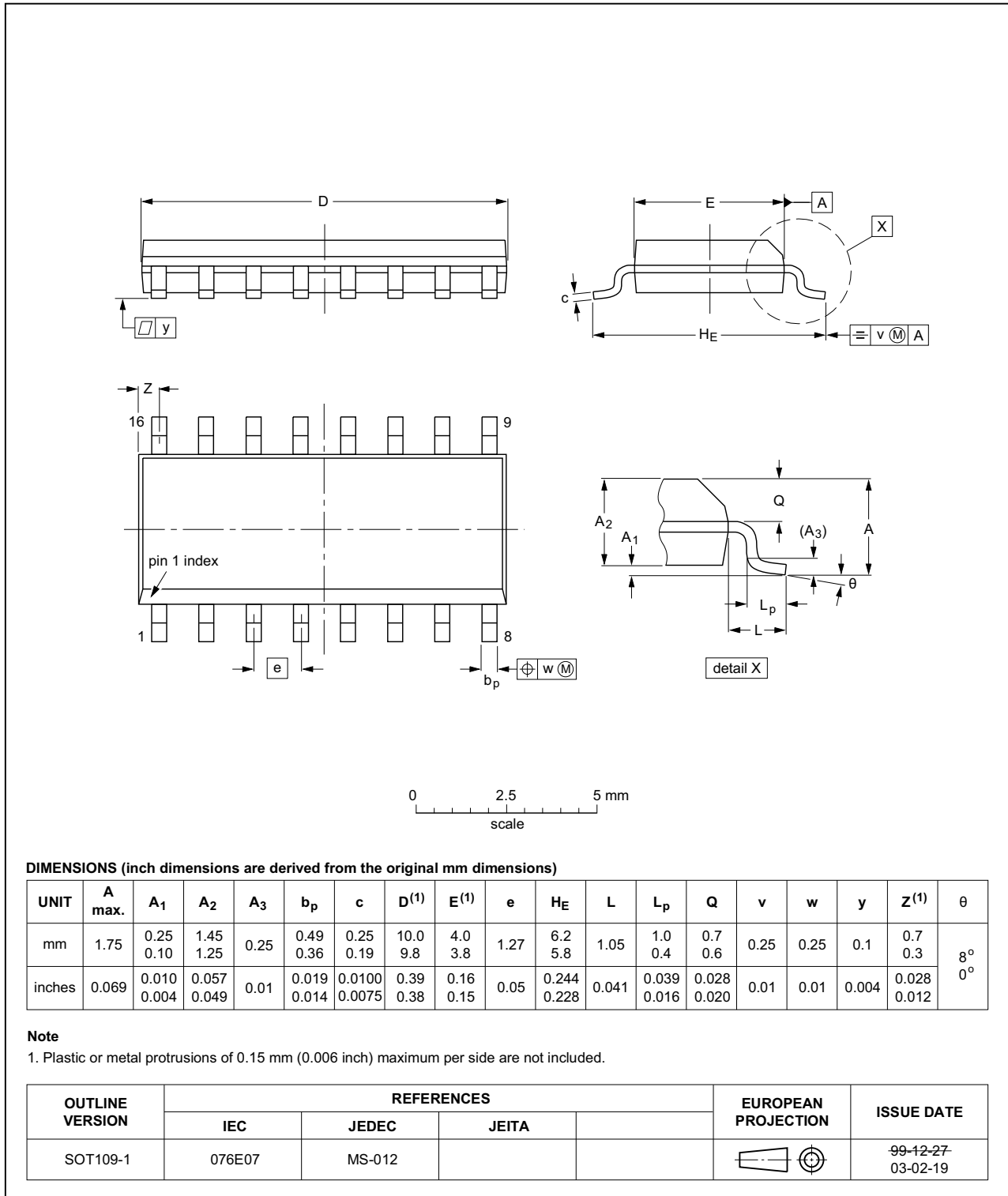


Fig 10. Package outline SOT109-1 (SO16)

SSOP16: plastic shrink small outline package; 16 leads; body width 5.3 mm

SOT338-1

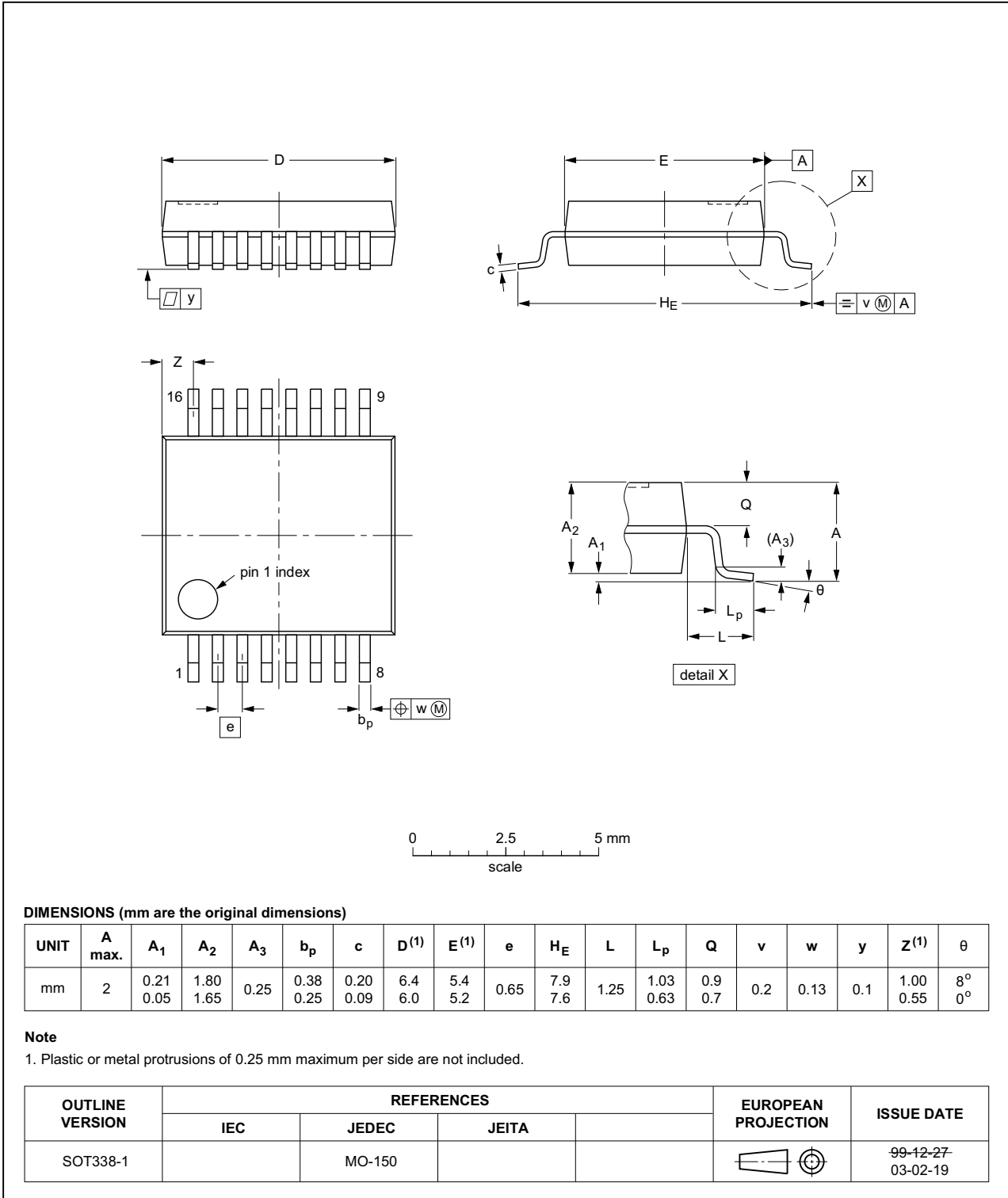


Fig 11. Package outline SOT338-1 (SSOP16)



## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC_HCT253 v.5	20150121	Product data sheet	-	74HC_HCT253 v.4
Modifications:	<ul style="list-style-type: none"> <li><a href="#">Table 7</a>: Power dissipation capacitance condition for 74HCT253 is corrected.</li> </ul>			
74HC_HCT253 v.4	20111212	Product data sheet	-	74HC_HCT253 v.3
Modifications:	<ul style="list-style-type: none"> <li>Legal pages updated.</li> </ul>			
74HC_HCT253 v.3	20100422	Product data sheet	-	74HC_HCT253_CNV v.2
74HC_HCT253_CNV v.2	970828	Product specification	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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